Icemos Technology Ltd **Product Specification** **1003.723801** Issue Date 16 May 2024 12:22:5

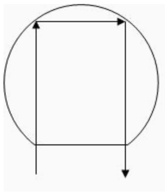
Part Number Customer

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.20 mm	WaferVendor
	2.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	3.0	Primary Flat Orientation	{110}+/- 0.5 degree	Wafer Vendor
	4.0	Secondary Flat Orientation	None	
	5.0	Type	Prime Grade Silicon	Wafer Vendor
	6.0	Overall Thickness	625.00 +/- 15.00 um	ADE 100% SEMI MF533
	7.0	Total Thickness Variation (TTV)	<5.00um	Guaranteed by process
	8.0	Bow	<40.00um	ADE to ASTM F534, 20%
	9.0	Warp	<40.00um	ADE to ASTM F657, 20%
	10.0	Back Surface Quality	Polished with light handling marks	Guaranteed by process
	11.0	Front Surface Quality	Polished (Prime)	Guaranteed by process
	12.0	Lasermarking	Backside, IceMOS Standard Scribe format	Guaranteed by Process
	13.0	Edge Chips	None	Bright Light 100%
	14.0	Edge Exclusion	5mm	
HandleSilicon	15.0	Handle Thickness	625.00 +/- 15.00 um	ADE 100% SEMI MF533
	16.0	Handle Growth Method	FZ	Wafer Vendor
	17.0	Handle Doping Type	P	Wafer Vendor
	18.0	Handle Dopant	Boron	Wafer Vendor
	19.0	Handle Resistivity	10000 ~ 15000 Ohm-cm	Wafer Vendor
	20.0	Handle Oxygen Concentration	SEMI Std	Wafer Vendor
	21.0	Handle Carbon Concentration	SEMI Std	Wafer Vendor
	22.0	Handle Orientation	{100} +/- 0.5 degree	Wafer Vendor
	23.0	Surface Haze	None	Bright Light, 100% (note 2).
	24.0	Total scratch length	None on the frontside, light handling marks on the backside	Bright Light, 100% (note 2).

Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	

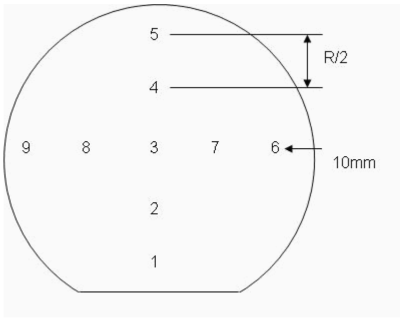
Explanatory Notes

1. Microscope inspection performed using microscope scan as below. 5x objective.



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information